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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/029,764
Applicant : Wen-Kun Yang
Filed : October 22, 2001
**Title : WAFER LEVEL PACKAGE FOR PRODUCING
CHIP SIZE PACKAGES AND METHOD OF
FABRICATING THE SAME**
Examiner : WILLIAMS, ALEXANDER O
Docket No. : 6033.P075

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Official Action mailed October 6, 2003, please amend the above-identified application as follows :

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims, which begin on page 15 of this paper.

Amendments to the Abstract begin on page 17 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 19 of this paper.

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